60V, 30A, 28mΩ N-channel Power Trench MOSFET

JMTK290N06A

Features

- $\bullet \;\;$ Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED
- 100% ΔVds TESTED
- Halogen-free; RoHS-compliant
- Pb-free plating

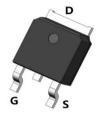
Applications

- Load Switch
- PWM Application
- Power Management

Product Summary

Parameters	Value	Unit
V_{DSS}	60	V
$V_{GS(th)_Typ}$	1.6	V
$I_D(@V_{GS}=10V)$	30	Α
$R_{DS(ON)_Typ}(@V_{GS}=10V$	25	mΩ
$R_{DS(ON)_Typ}(@V_{GS}=4.5V$	28	mΩ

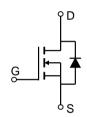








Pin Assignment



Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMTK290N06A	JMTK290N06A	3	Tape&Reel	TO-252-3L	2500	25000

Absolute Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Symbol	Parameter	Parameter		Unit
V_{DS}	Drain-to-Source Voltage		60	V
V_{GS}	Gate-to-Source Voltage	Gate-to-Source Voltage		V
L	Continuous Drain Current	$T_C = 25^{\circ}C$	30	Α
I _D	Continuous Drain Current	$T_C = 100$ °C	19	
I _{DM}	Pulsed Drain Current (1)	Pulsed Drain Current (1)		Α
E _{AS}	Single Pulsed Avalanche Energ	Single Pulsed Avalanche Energy (2)		mJ
P_{D}	Power Dissipation	$T_C = 25^{\circ}C$	37	W
' D	Fower Dissipation	$T_C = 100$ °C	15	
T_{J}, T_{STG}	Junction & Storage Temperature	Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Max	Unit		
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (3)	39	°C/W		
Raic	Thermal Resistance, Junction to Case	3.4	C/VV		



Electrical Characteristics (T_J = 25°C unless otherwise specified)

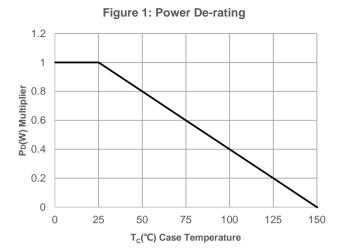
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 60V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics				•	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1	1.6	2.5	V
R	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10V, I_D = 20A$	-	25	29	mΩ
R _{DS(ON)}	Static Drain-Source ON-Resistance	$V_{GS} = 4.5V, I_D = 15A$	-	28	40	mΩ
Dynami	ic Characteristics					
R_{g}	Gate Resistance	f = 1MHz	-	2.4	-	Ω
C _{iss}	Input Capacitance	.,	1021	1430	1930	pF
C _{oss}	Output Capacitance		47	66	89	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112	39	54	73	pF
Qg	Total Gate Charge		20	28	38	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0V, V_{DS} = 30V,$ $f = 1MHz$ $V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 30V, I_{D} = 20A$	4	6	8	nC
Q_{gd}	Gate Drain("Miller") Charge	V DS = 30 V, ID = 20A	4	5	7	nC
Switchi	ng Characteristics					
t _{d(on)}	Turn-On DelayTime		-	6	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 30V$	-	14	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 20A, R_{GEN} = 3\Omega$	-	26	-	ns
t _f	Turn-Off Fall Time		-	4	-	ns
Body D	iode Characteristics					
Is	Maximum Continuous Body Diode Forward (Current	-	-	30	Α
I _{SM}	Maximum Pulsed Body Diode Forward Curre	ent	-	-	120	Α
V _{SD}	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 20A$	-		1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 20A, di/dt = 100A/us	16	23	31	ns
Qrr	Body Diode Reverse Recovery Charge	$r_F = 20$ A, $ui/ui = 100$ A/uS	-	28	-	nC

Notes:

- ${\bf 1.}\ {\bf Repetitive}\ {\bf Rating:}\ {\bf Pulse}\ {\bf Width}\ {\bf Limited}\ {\bf by}\ {\bf Maximum}\ {\bf Junction}\ {\bf Temperature}.$
- $2.~E_{AS}~condition:~Starting~T_J=25C,~V_{DD}=30V,~V_G=10V,~R_G=25ohm,~L=0.5mH,~I_{AS}=10.92A,~V_{DD}=0V~during~time~in~avalanche.$
- 3. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB.
- 4. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.



Typical Performance Characteristics



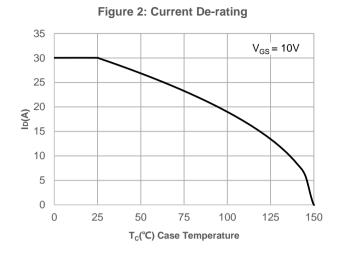
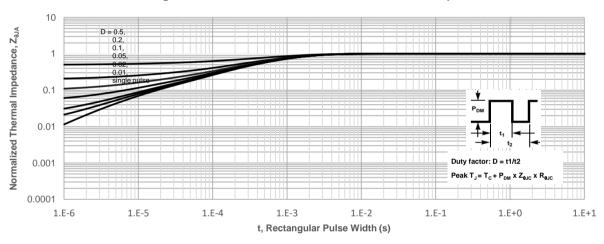
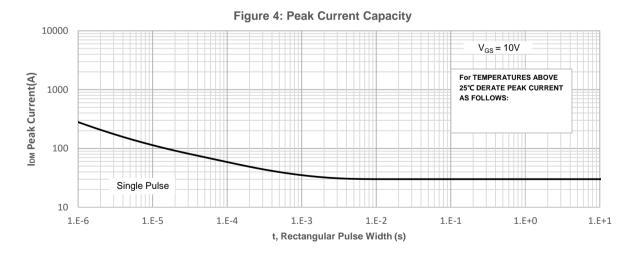


Figure 3: Normalized Maximum Transient Thermal Impedance







Typical Performance Characteristics

Figure 5: Output Characteristics

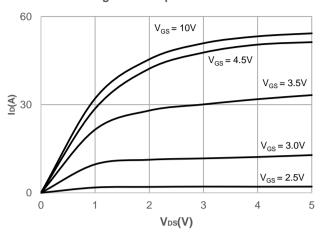


Figure 6: Typical Transfer Characteristics

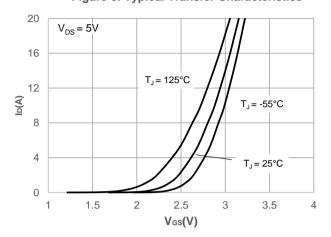


Figure 7: On-resistance vs. Drain Current

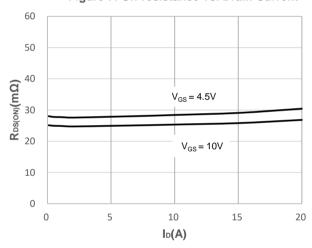


Figure 8: Body Diode Characteristics

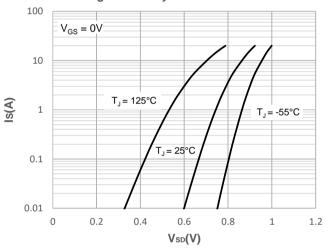
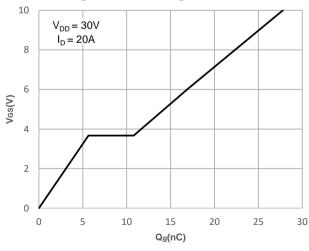
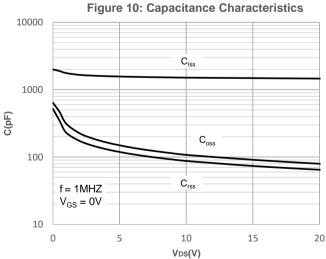


Figure 9: Gate Charge Characteristics







Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs.
Junction Temperature

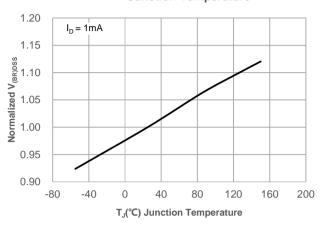


Figure 13: Normalized Threshold Voltage vs.
Junction Temperature

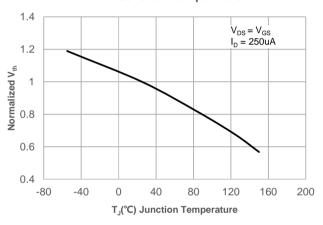


Figure 15: Maximum Safe Operating Area

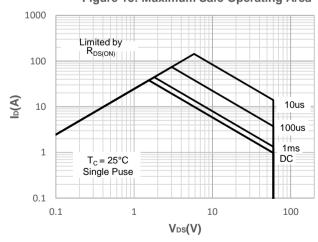
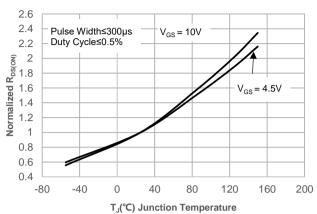
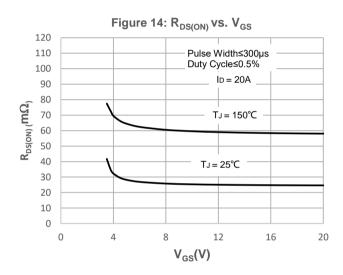


Figure 12: Normalized on Resistance vs.
Junction Temperature







Test Circuit

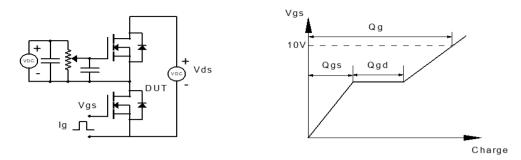


Figure 1: Gate Charge Test Circuit & Waveform

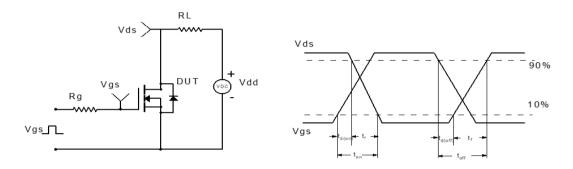


Figure 2: Resistive Switching Test Circuit & Waveform

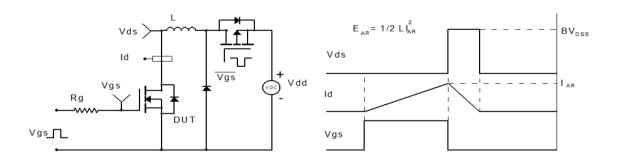


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

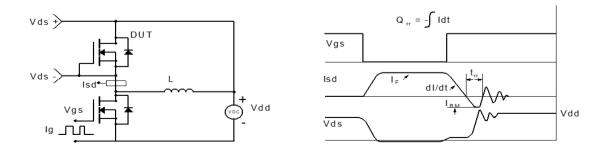
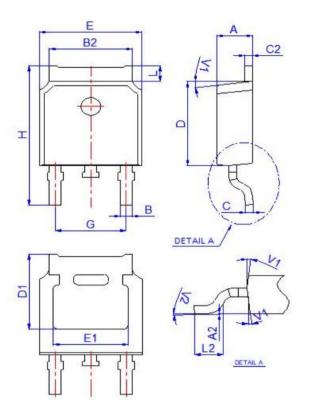


Figure 4: Diode Recovery Test Circuit & Waveform



Package Mechanical Data(TO-252-3L)



			Dime	ensions		
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°	2	6°

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